**Product data sheet** 

### 1. General description

The 74HC165; 74HCT165 are 8-bit serial or parallel-in/serial-out shift registers. The device features a serial data input (DS), eight parallel data inputs (D0 to D7) and two complementary serial outputs (Q7 and  $\overline{\rm Q7}$ ). When the parallel load input ( $\overline{\rm PL}$ ) is LOW the data from D0 to D7 is loaded into the shift register asynchronously. When  $\overline{\rm PL}$  is HIGH data enters the register serially at DS. When the clock enable input ( $\overline{\rm CE}$ ) is LOW data is shifted on the LOW-to-HIGH transitions of the CP input. A HIGH on  $\overline{\rm CE}$  will disable the CP input. Inputs are overvoltage tolerant to 15 V. This enables the device to be used in HIGH-to-LOW level shifting applications.

### 2. Features and benefits

- Wide supply voltage range from 2.0 V to 6.0 V
- · CMOS low power dissipation
- · High noise immunity
- Latch-up performance exceeds 100 mA per JESD 78 Class II Level B
- · Asynchronous 8-bit parallel load
- · Synchronous serial input
- · Input levels:
  - For 74HC165: CMOS level
  - For 74HCT165: TTL level
- Complies with JEDEC standards:
  - JESD8C (2.7 V to 3.6 V)
  - JESD7A (2.0 V to 6.0 V)
- ESD protection:
  - HBM: ANSI/ESDA/JEDEC JS-001 class 2 exceeds 2000 V
  - CDM: ANSI/ESDA/JEDEC JS-002 class C3 exceeds 1000 V
- Multiple package options
- Specified from -40 °C to +85 °C and from -40 °C to +125 °C

# 3. Applications

Parallel-to-serial data conversion

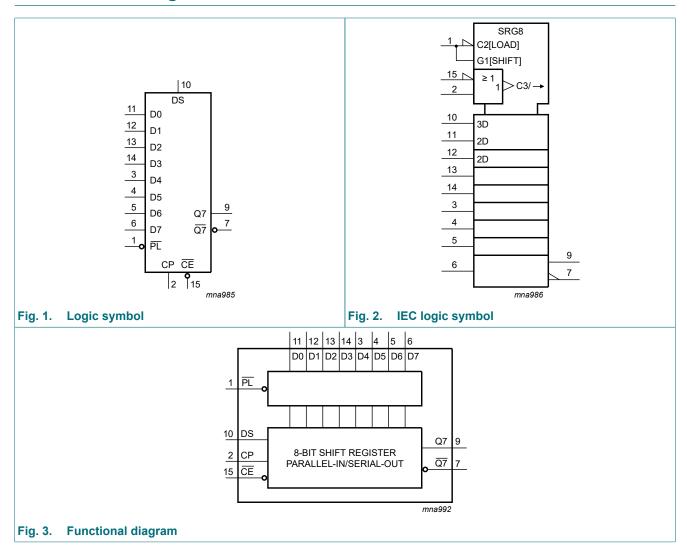


# 4. Ordering information

**Table 1. Ordering information** 

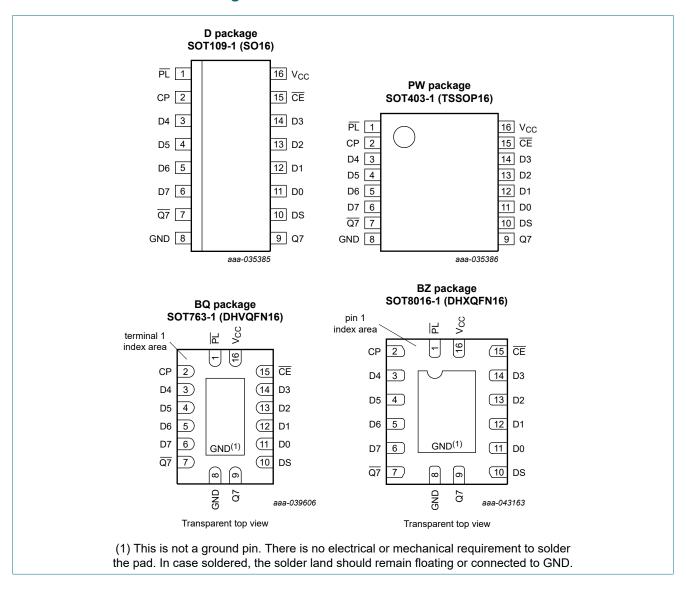
Type number	Package			
	Temperature range	Name	Description	Version
74HC165D 74HCT165D	-40 °C to +125 °C	SO16	plastic small outline package; 16 leads; body width 3.9 mm	SOT109-1
74HC165PW 74HCT165PW	-40 °C to +125 °C	TSSOP16	plastic thin shrink small outline package; 16 leads; body width 4.4 mm	SOT403-1
74HC165BQ 74HCT165BQ	-40 °C to +125 °C	DHVQFN16	plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 16 terminals; body 2.5 × 3.5 × 0.85 mm	SOT763-1
74HC165BZ 74HCT165BZ	-40 °C to +125 °C	DHXQFN16	plastic, leadless dual in-line compatible thermal enhanced extreme thin quad flat package; no leads; 16 terminals; 0.4 mm pitch; body 2 mm × 2.4 mm × 0.48 mm	SOT8016-1

# 5. Functional diagram



# 6. Pinning information

### 6.1. Pinning



## 6.2. Pin description

Table 2. Pin description

Symbol	Pin	Description
PL	1	asynchronous parallel load input (active LOW)
CP	2	clock input (LOW-to-HIGH edge-triggered)
Q7	7	complementary output from the last stage
GND	8	ground (0 V)
Q7	9	serial output from the last stage
DS	10	serial data input
D0 to D7	11, 12, 13, 14, 3, 4, 5, 6	parallel data inputs (also referred to as Dn)
CE	15	clock enable input (active LOW)
V <sub>CC</sub>	16	positive supply voltage

# 7. Functional description

#### Table 3. Function table

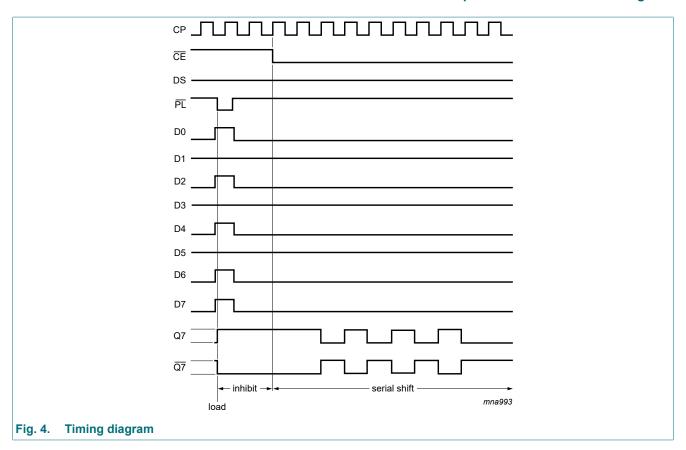
 $H = HIGH \ voltage \ level; \ h = HIGH \ voltage \ level \ one \ set-up \ time \ prior \ to \ the \ LOW-to-HIGH \ clock \ transition;$ 

L = LOW voltage level; I = LOW voltage level one set-up time prior to the LOW-to-HIGH clock transition;

*q* = state of the referenced output one set-up time prior to the LOW-to-HIGH clock transition;

X = don't care;  $\uparrow = LOW-to-HIGH clock transition$ .

Operating modes	Inputs					Qn regist	ers	Outputs	
	PL	CE	СР	DS	D0 to D7	Q0	Q1 to Q6	Q7	Q7
parallel load	L	X	X	X	L	L	L to L	L	Н
	L	Х	Х	Х	Н	Н	H to H	Н	L
serial shift	Н	L	1	I	X	L	q0 to q5	q6	<del>q6</del>
	Н	L	1	h	X	Н	q0 to q5	q6	<del>q6</del>
	Н	1	L	I	X	L	q0 to q5	q6	<del>q6</del>
	Н	1	L	h	X	Н	q0 to q5	q6	<del>q</del> 6
hold "do nothing"	Н	Н	X	Х	Х	q0	q1 to q6	q7	<del>q</del> 7
	Н	X	Н	X	X	q0	q1 to q6	q7	<del>q7</del>



# 8. Limiting values

#### **Table 4. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V)

Symbol	Parameter	Conditions		Min	Max	Unit
V <sub>CC</sub>	supply voltage			-0.5	+7	V
I <sub>IK</sub>	input clamping current	$V_{I} < -0.5 \text{ V or } V_{I} > V_{CC} + 0.5 \text{ V}$	[1]	-	±20	mA
I <sub>OK</sub>	output clamping current	$V_{O}$ < -0.5 V or $V_{O}$ > $V_{CC}$ + 0.5 V	[1]	-	±20	mA
I <sub>O</sub>	output current	$-0.5 \text{ V} < \text{V}_{\text{O}} < \text{V}_{\text{CC}} + 0.5 \text{ V}$		-	±25	mA
I <sub>CC</sub>	supply current			-	50	mA
I <sub>GND</sub>	ground current			-50	-	mA
T <sub>stg</sub>	storage temperature			-65	+150	°C
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> = -40 °C to +125 °C				
		SOT109-1 (SO16) SOT403-1 (TSSOP16) SOT763-1 (DHVQFN16)	[2] [3] [4]	-	500	mW
		SOT8016-1 (DHXQFN16)		-	250	mW

- The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
- For SOT109-1 (SO16) package: Ptot derates linearly with 12.4 mW/K above 110 °C.
- [3]
- For SOT403-1 (TSSOP16) package: P<sub>tot</sub> derates linearly with 8.5 mW/K above 91 °C. For SOT763-1 (DHVQFN16) package: P<sub>tot</sub> derates linearly with 11.2 mW/K above 106 °C.

# 9. Recommended operating conditions

#### Table 5. Recommended operating conditions

Voltages are referenced to GND (ground = 0 V)

Symbol	Parameter	Conditions		74HC165	5	7	4HCT16	5	Unit
			Min	Тур	Max	Min	Тур	Max	
V <sub>CC</sub>	supply voltage		2.0	5.0	6.0	4.5	5.0	5.5	V
VI	input voltage		0	-	V <sub>CC</sub>	0	-	V <sub>CC</sub>	V
Vo	output voltage		0	-	V <sub>CC</sub>	0	-	V <sub>CC</sub>	V
T <sub>amb</sub>	ambient temperature		-40	-	+125	-40	-	+125	°C
Δt/ΔV	input transition rise and fall rate	V <sub>CC</sub> = 2.0 V	-	-	625	-	-	-	ns/V
		V <sub>CC</sub> = 4.5 V	-	1.67	139	-	1.67	139	ns/V
		V <sub>CC</sub> = 6.0 V	-	-	83	-	-	-	ns/V

## 10. Static characteristics

#### **Table 6. Static characteristics**

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions		25 °C		-40 °C to +85 °C		-40 °C to +125 °C		Unit
			Min	Тур	Max	Min	Max	Min	Max	
74HC16	5									
V <sub>IH</sub>	HIGH-level input	V <sub>CC</sub> = 2.0 V	1.5	1.2	-	1.5	-	1.5	-	V
	voltage	V <sub>CC</sub> = 4.5 V	3.15	2.4	-	3.15	-	3.15	-	V
		V <sub>CC</sub> = 6.0 V	4.2	3.2	-	4.2	-	4.2	-	V
V <sub>IL</sub>	LOW-level input	V <sub>CC</sub> = 2.0 V	-	0.8	0.5	-	0.5	-	0.5	V
	voltage	V <sub>CC</sub> = 4.5 V	-	2.1	1.35	-	1.35	-	1.35	V
		V <sub>CC</sub> = 6.0 V	-	2.8	1.8	-	1.8	-	1.8	V
V <sub>OH</sub>	HIGH-level	$V_I = V_{IH}$ or $V_{IL}$								
	output voltage	I <sub>O</sub> = -20 μA; V <sub>CC</sub> = 2.0 V	1.9	2.0	-	1.9	-	1.9	-	V
		I <sub>O</sub> = -20 μA; V <sub>CC</sub> = 4.5 V	4.4	4.5	-	4.4	-	4.4	-	V
		I <sub>O</sub> = -20 μA; V <sub>CC</sub> = 6.0 V	5.9	6.0	-	5.9	-	5.9	-	V
		I <sub>O</sub> = -4.0 mA; V <sub>CC</sub> = 4.5 V	3.98	4.32	-	3.84	-	3.7	-	V
		I <sub>O</sub> = -5.2 mA; V <sub>CC</sub> = 6.0 V	5.48	5.81	-	5.34	-	5.2	-	V
V <sub>OL</sub>	LOW-level	$V_I = V_{IH}$ or $V_{IL}$								
	output voltage	I <sub>O</sub> = 20 μA; V <sub>CC</sub> = 2.0 V	-	0	0.1	-	0.1	-	0.1	V
		I <sub>O</sub> = 20 μA; V <sub>CC</sub> = 4.5 V	-	0	0.1	-	0.1	-	0.1	V
		I <sub>O</sub> = 20 μA; V <sub>CC</sub> = 6.0 V	-	0	0.1	-	0.1	-	0.1	V
		I <sub>O</sub> = 4.0 mA; V <sub>CC</sub> = 4.5 V	-	0.15	0.26	-	0.33	-	0.4	V
		I <sub>O</sub> = 5.2 mA; V <sub>CC</sub> = 6.0 V	-	0.16	0.26	-	0.33	-	0.4	V
l <sub>l</sub>	input leakage current	$V_I = V_{CC}$ or GND; $V_{CC} = 6.0 \text{ V}$	-	-	±0.1	-	±1	-	±1	μΑ
I <sub>CC</sub>	supply current	$V_I = V_{CC}$ or GND; $I_O = 0$ A; $V_{CC} = 6.0 \text{ V}$	-	-	8.0	-	80	-	160	μΑ
C <sub>I</sub>	input capacitance		-	3.5	-	-	-	-	-	pF

Symbol	Parameter	Conditions		25 °C			°C to 5 °C		°C to 5 °C	Unit
			Min	Тур	Max	Min	Max	Min	Max	
74HCT1	65		'							
V <sub>IH</sub>	HIGH-level input voltage	V <sub>CC</sub> = 4.5 V to 5.5 V	2.0	1.6	-	2.0	-	2.0	-	V
V <sub>IL</sub>	LOW-level input voltage	V <sub>CC</sub> = 4.5 V to 5.5 V	-	1.2	0.8	-	0.8	-	0.8	V
V <sub>OH</sub>	HIGH-level	$V_I = V_{IH}$ or $V_{IL}$ ; $V_{CC} = 4.5 V$								
	output voltage	I <sub>O</sub> = -20 μA	4.4	4.5	-	4.4	-	4.4	-	V
		I <sub>O</sub> = -4.0 mA	3.98	4.32	-	3.84	-	3.7	-	V
V <sub>OL</sub>	LOW-level	$V_I = V_{IH}$ or $V_{IL}$								
	output voltage	I <sub>O</sub> = 20 μA; V <sub>CC</sub> = 4.5 V	-	0	0.1	-	0.1	-	0.1	V
		I <sub>O</sub> = 5.2 mA; V <sub>CC</sub> = 6.0 V	-	0.16	0.26	-	0.33	-	0.4	V
I <sub>I</sub>	input leakage current	$V_I = V_{CC}$ or GND; $V_{CC} = 6.0 \text{ V}$	-	-	±0.1	-	±1	-	±1	μA
I <sub>CC</sub>	supply current	$V_I = V_{CC}$ or GND; $I_O = 0$ A; $V_{CC} = 6.0 \text{ V}$	-	-	8.0	-	80	-	160	μA
ΔI <sub>CC</sub>	additional supply current	per input pin; $V_I = V_{CC} - 2.1 \text{ V}$ ; other inputs at $V_{CC}$ or GND; $V_{CC} = 4.5 \text{ V}$ to 5.5 V								
		Dn and DS inputs	-	35	126	-	157.5	-	171.5	μA
		CP, CE, and PL inputs	-	65	234	-	292.5	-	318.5	μΑ
Cı	input capacitance		-	3.5	-	-	-	-	-	pF

# 11. Dynamic characteristics

#### **Table 7. Dynamic characteristics**

At recommended operating conditions; voltages are referenced to GND (ground = 0 V);  $C_L = 50 \text{ pF}$  unless otherwise specified; for test circuit, see Fig. 10

Symbol	Parameter	Conditions		25 °C			°C to 5 °C		°C to 5 °C	Unit
			Min	Тур	Max	Min	Max	Min	Max	
74HC16	5									
t <sub>pd</sub>	propagation	CP or CE to Q7, Q7; see Fig. 5 [1]								
	delay	V <sub>CC</sub> = 2.0 V	-	52	165	-	205	-	250	ns
		V <sub>CC</sub> = 4.5 V	-	19	33	-	41	-	50	ns
		V <sub>CC</sub> = 6.0 V	-	15	28	-	35	-	43	ns
		V <sub>CC</sub> = 5.0 V; C <sub>L</sub> = 15 pF	-	16	-	-	-	-	-	ns
		PL to Q7, Q7; see Fig. 6								
		V <sub>CC</sub> = 2.0 V	-	50	165	-	205	-	250	ns
		V <sub>CC</sub> = 4.5 V	-	18	33	-	41	-	50	ns
		V <sub>CC</sub> = 6.0 V	-	14	28	-	35	-	43	ns
		V <sub>CC</sub> = 5.0 V; C <sub>L</sub> = 15 pF	-	15	-	-	-	-	-	ns
		D7 to Q7, Q7; see Fig. 7								
		V <sub>CC</sub> = 2.0 V	-	36	120	-	150	-	180	ns
		V <sub>CC</sub> = 4.5 V	-	13	24	-	30	-	36	ns
		V <sub>CC</sub> = 6.0 V	-	10	20	-	26	-	31	ns
		V <sub>CC</sub> = 5.0 V; C <sub>L</sub> = 15 pF	-	11	-	-	-	-	-	ns
t <sub>t</sub>	transition time	Q7, Q7 output; see Fig. 5 [2]								
		V <sub>CC</sub> = 2.0 V	-	19	75	-	95	-	110	ns
		V <sub>CC</sub> = 4.5 V	-	7	15	-	19	-	22	ns
		V <sub>CC</sub> = 6.0 V	-	6	13	-	16	-	19	ns
t <sub>W</sub>	pulse width	CP input HIGH or LOW; see Fig. 5								
		V <sub>CC</sub> = 2.0 V	80	17	-	100	-	120	-	ns
		V <sub>CC</sub> = 4.5 V	16	6	-	20	-	24	-	ns
		V <sub>CC</sub> = 6.0 V	14	5	-	17	-	20	-	ns
		PL input LOW; see Fig. 6								
		V <sub>CC</sub> = 2.0 V	80	14	-	100	-	120	-	ns
		V <sub>CC</sub> = 4.5 V	16	5	-	20	-	24	-	ns
		V <sub>CC</sub> = 6.0 V	14	4	-	17	-	20	-	ns
t <sub>rec</sub>	recovery time	PL to CP, CE; see Fig. 6								
		V <sub>CC</sub> = 2.0 V	100	22	-	125	-	150	-	ns
		V <sub>CC</sub> = 4.5 V	20	8	-	25	-	30	-	ns
ı		V <sub>CC</sub> = 6.0 V	17	6	_	21	-	26	-	ns

8 / 20

Symbol	Parameter	Conditions		25 °C			°C to		°C to 5 °C	Unit
			Min	Тур	Max	Min	Max	Min	Max	
t <sub>su</sub>	set-up time	DS to CP, CE; see Fig. 8								
		V <sub>CC</sub> = 2.0 V	80	11	-	100	-	120	-	ns
		V <sub>CC</sub> = 4.5 V	16	4	-	20	-	24	-	ns
		V <sub>CC</sub> = 6.0 V	14	3	-	17	-	20	-	ns
		CE to CP and CP to CE; see Fig. 8								
		V <sub>CC</sub> = 2.0 V	80	17	-	100	-	120	-	ns
		V <sub>CC</sub> = 4.5 V	16	6	-	20	-	24	-	ns
		V <sub>CC</sub> = 6.0 V	14	5	-	17	-	20	-	ns
		Dn to PL; see Fig. 9								
		V <sub>CC</sub> = 2.0 V	80	22	-	100	-	120	-	ns
		V <sub>CC</sub> = 4.5 V	16	8	-	20	-	24	-	ns
		V <sub>CC</sub> = 6.0 V	14	6	-	17	-	20	-	ns
t <sub>h</sub>	hold time	DS to CP, CE and Dn to PL; see Fig. 8								
		V <sub>CC</sub> = 2.0 V	5	2	-	5	-	5	-	ns
		V <sub>CC</sub> = 4.5 V	5	2	-	5	-	5	-	ns
		V <sub>CC</sub> = 6.0 V	5	2	-	5	-	5	-	ns
		CE to CP and CP to CE; see Fig. 8								
		V <sub>CC</sub> = 2.0 V	5	-17	-	5	-	5	-	ns
		V <sub>CC</sub> = 4.5 V	5	-6	-	5	-	5	-	ns
		V <sub>CC</sub> = 6.0 V	5	-5	-	5	-	5	-	ns
f <sub>max</sub>	maximum	CP input; see Fig. 5								
	frequency	V <sub>CC</sub> = 2.0 V	6	17	-	5	-	4	-	MHz
		V <sub>CC</sub> = 4.5 V	30	51	-	24	-	20	-	MHz
		V <sub>CC</sub> = 6.0 V	35	61	-	28	-	24	-	MHz
		V <sub>CC</sub> = 5.0 V; C <sub>L</sub> = 15 pF	-	56	-	-	-	-	-	MHz
C <sub>PD</sub>	power dissipation capacitance	per package; $V_I = GND$ to $V_{CC}$ [3]	-	35	-	-	-	-	-	pF
74HCT1	<u> </u>									
t <sub>pd</sub>	propagation	CE, CP to Q7, Q7; see Fig. 5 [1]								
ъри	delay	V <sub>CC</sub> = 4.5 V	_	17	34	_	43	_	51	ns
		$V_{CC} = 5.0 \text{ V}; C_L = 15 \text{ pF}$	_	14	_	_	-	_	_	ns
		$\overline{PL}$ to Q7, $\overline{Q7}$ ; see $\overline{Fig. 6}$								+
		V <sub>CC</sub> = 4.5 V	_	20	40	_	50	_	60	ns
		$V_{CC} = 5.0 \text{ V}; C_L = 15 \text{ pF}$	_	17	-	_	-	_	-	ns
		D7 to Q7, Q7; see Fig. 7		.,						
		$V_{CC} = 4.5 \text{ V}$	_	14	28	-	35	_	42	ns
		$V_{CC} = 5.0 \text{ V}; C_L = 15 \text{ pF}$	_	11	-	-	-	_	-	ns

Symbol	Parameter	Conditions		25 °C		-40 °C to +85 °C		-40 °C to +125 °C		Unit
			Min	Тур	Max	Min	Max	Min	Max	
t <sub>t</sub>	transition time	Q7, Q7 output; see Fig. 5 [2]								
		V <sub>CC</sub> = 4.5 V	-	7	15	-	19	-	22	ns
t <sub>W</sub>	pulse width	CP input; see Fig. 5								
		V <sub>CC</sub> = 4.5 V	16	6	-	20	-	24	-	ns
		PL input; see Fig. 6								
		V <sub>CC</sub> = 4.5 V	20	9	-	25	-	30	-	ns
t <sub>rec</sub>	recovery time	PL to CP, CE; see Fig. 6								
		V <sub>CC</sub> = 4.5 V	20	8	-	25	-	30	-	ns
t <sub>su</sub>	set-up time	DS to CP, CE; see Fig. 8								
		V <sub>CC</sub> = 4.5 V	20	2	-	25	-	30	-	ns
		CE to CP and CP to CE; see Fig. 8								
		V <sub>CC</sub> = 4.5 V	20	7	-	25	-	30	-	ns
		Dn to PL; see Fig. 9								
		V <sub>CC</sub> = 4.5 V	20	10	-	25	-	30	-	ns
t <sub>h</sub>	hold time	DS to CP, CE and Dn to PL; see Fig. 8								
		V <sub>CC</sub> = 4.5 V	7	-1	-	9	-	11	-	ns
		CE to CP and CP to CE; see Fig. 8								
		V <sub>CC</sub> = 4.5 V	0	-7	-	0	-	0	-	ns
f <sub>max</sub>	maximum	CP input; see Fig. 5								
	frequency	V <sub>CC</sub> = 4.5 V	26	44	-	21	-	17	-	MHz
		V <sub>CC</sub> = 5.0 V; C <sub>L</sub> = 15 pF	-	48	-	-	-	-	-	MHz
C <sub>PD</sub>	power dissipation capacitance	per package; [3] V <sub>I</sub> = GND to V <sub>CC</sub> - 1.5 V	-	35	-	-	-	-	-	pF

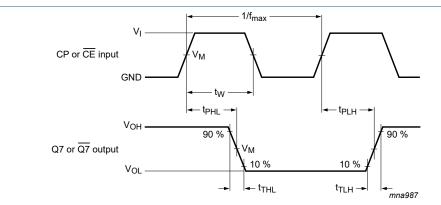
 $f_o$  = output frequency in MHz;  $\Sigma$  ( $C_L \times V_{CC}^2 \times f_o$ ) = sum of outputs;  $C_L$  = output load capacitance in pF;

V<sub>CC</sub> = supply voltage in V.

10 / 20

 $<sup>\</sup>begin{array}{ll} [1] & t_{pd} \text{ is the same as } t_{PHL} \text{ and } t_{PLH}. \\ [2] & t_{t} \text{ is the same as } t_{THL} \text{ and } t_{TLH}. \\ [3] & C_{PD} \text{ is used to determine the dynamic power dissipation } (P_{D} \text{ in } \mu W). \\ & P_{D} = C_{PD} \times V_{CC}^{2} \times f_{i} + \Sigma \left(C_{L} \times V_{CC}^{2} \times f_{o}\right) \text{ where:} \\ & f_{i} = \text{input frequency in MHz;} \end{array}$ 

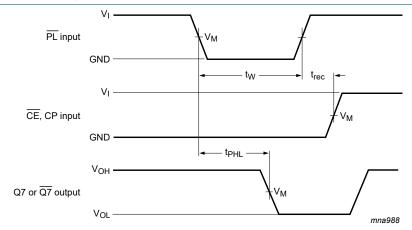
### 11.1. Waveforms and test circuit



Measurement points are given in Table 8.

V<sub>OL</sub> and V<sub>OH</sub> are typical voltage output levels that occur with the output load.

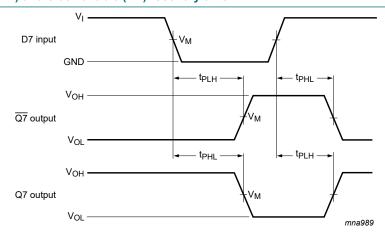
Fig. 5. The clock (CP) or clock enable (CE) to output (Q7 or Q7) propagation delays, the clock pulse width, the maximum clock frequency and the output transition times



Measurement points are given in Table 8.

V<sub>OL</sub> and V<sub>OH</sub> are typical voltage output levels that occur with the output load.

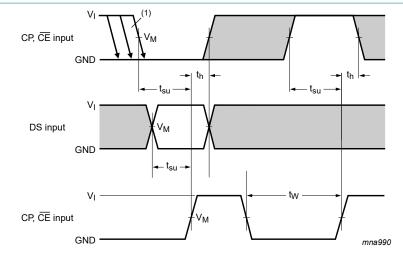
Fig. 6. The parallel load (PL) pulse width, the parallel load to output (Q7 or Q7) propagation delays, the parallel load to clock (CP) and clock enable (CE) recovery time



Measurement points are given in Table 8.

 $V_{OL}$  and  $V_{OH}$  are typical voltage output levels that occur with the output load.

Fig. 7. The data input (D7) to output (Q7 or  $\overline{Q7}$ ) propagation delays when  $\overline{PL}$  is LOW

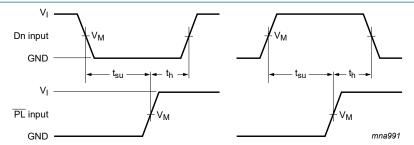


(1)  $\overline{\text{CE}}$  may change only from HIGH-to-LOW while CP is LOW.

The shaded areas indicate when the input is permitted to change for predictable output performance Measurement points are given in <u>Table 8</u>.

 $V_{OL}$  and  $V_{OH}$  are typical voltage output levels that occur with the output load.

Fig. 8. The set-up and hold times from the serial data input (DS) to the clock (CP) and clock enable (CE) inputs, from the clock enable input (CE) to the clock input (CP) and from the clock input (CP) to the clock enable input (CE)



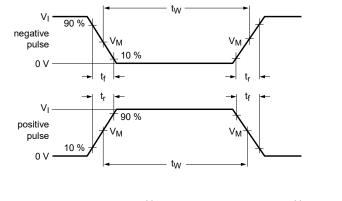
Measurement points are given in Table 8.

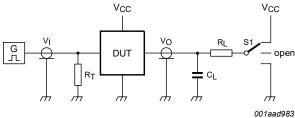
V<sub>OL</sub> and V<sub>OH</sub> are typical voltage output levels that occur with the output load.

Fig. 9. The set-up and hold times from the data inputs (Dn) to the parallel load input (PL)

**Table 8. Measurement points** 

Туре	Input	Output	
	VI	V <sub>M</sub>	V <sub>M</sub>
74HC165	V <sub>CC</sub>	0.5V <sub>CC</sub>	0.5V <sub>CC</sub>
74HCT165	3 V	1.3 V	1.3 V





Test data is given in Table 9.

Definitions test circuit:

 $R_T$  = Termination resistance should be equal to output impedance  $Z_o$  of the pulse generator;

C<sub>L</sub> = Load capacitance including jig and probe capacitance;

R<sub>I</sub> = Load resistance;

S1 = Test selection switch

Fig. 10. Test circuit for measuring switching times

Table 9. Test data

Туре	Input		Load		S1 position
	V <sub>I</sub>	t <sub>r</sub> , t <sub>f</sub>	C <sub>L</sub>	$R_L$	t <sub>PHL</sub> , t <sub>PLH</sub>
74HC165	V <sub>CC</sub>	6 ns	15 pF, 50 pF	1 kΩ	open
74HCT165	3 V	6 ns	15 pF, 50 pF	1 kΩ	open

# 12. Package outline

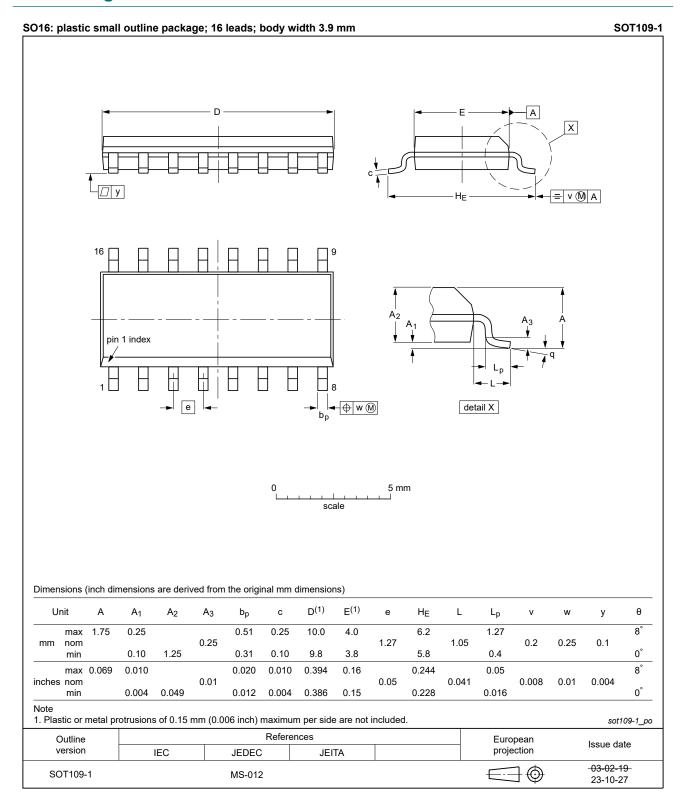


Fig. 11. Package outline SOT109-1 (SO16)

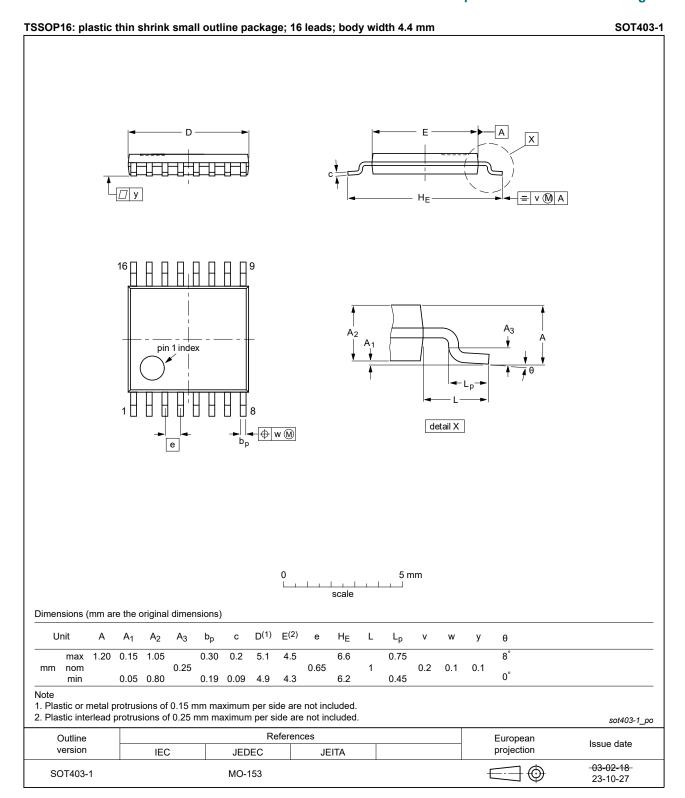


Fig. 12. Package outline SOT403-1 (TSSOP16)

DHVQFN16: plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 16 terminals; body 2.5 x 3.5 x 0.85 mm SOT763-1

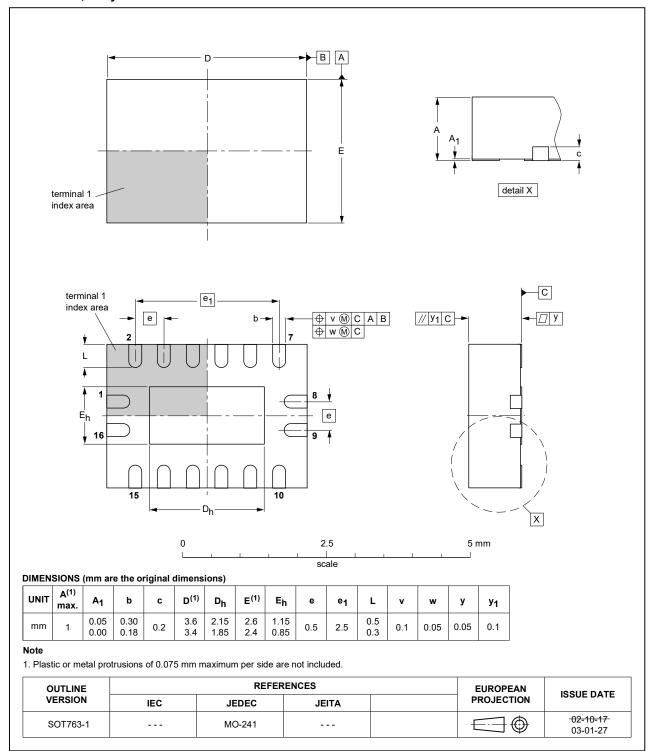


Fig. 13. Package outline SOT763-1 (DHVQFN16)

DHXQFN16: plastic, leadless dual in-line compatible thermal enhanced extreme thin quad flat package; no leads; 16 terminals; 0.4 mm pitch; body 2 mm x 2.4 mm x 0.48 mm

SOT8016-1

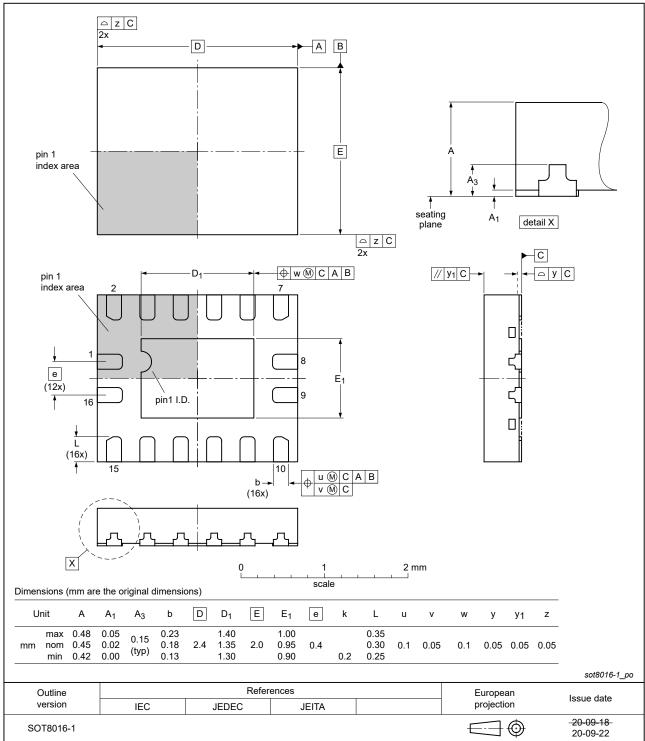


Fig. 14. Package outline SOT8016-1 (DHXQFN16)

## 13. Abbreviations

#### **Table 10. Abbreviations**

Acronym	Description
ANSI	American National Standards Institute
CDM	Charged Device Model
CMOS	Complementary Metal-Oxide Semiconductor
DUT	Device Under Test
ESD	ElectroStatic Discharge
ESDA	ElectroStatic Discharge Association
НВМ	Human Body Model
JEDEC	Joint Electron Device Engineering Council
TTL	Transistor-Transistor Logic

# 14. Revision history

### Table 11. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes		
74HC_HCT165 v.8	20250509	Product data sheet	-	74HC_HCT165 v.7		
Modifications:	• Fig. 11, Fig. and MO-15	<ul> <li>Type numbers 74HC165BZ and 74HCT165BZ (SOT8016-1/DHXQFN16) added.</li> <li>Fig. 11, Fig. 12: Aligned SO and TSSOP package outline drawings to JEDEC MS-012 and MO-153.</li> <li>Section 2: ESD specification updated according to the latest JEDEC standard.</li> </ul>				
74HC_HCT165 v.7	20210901	Product data sheet	-	74HC_HCT165 v.6		
Modifications:		<ul> <li>Section 2 updated.</li> <li>Type numbers 74HC165DB and 74HCT165DB (SOT338-1/SSOP16) removed.</li> </ul>				
74HC_HCT165 v.6	20200423	Product data sheet	-	74HC_HCT165 v.5		
Modifications:	• <u>Table 4</u> : De	<u>Table 4</u> : Derating values for P <sub>tot</sub> total power dissipation updated.				
74HC_HCT165 v.5	20170821	Product data sheet	-	74HC_HCT165 v.4		
Modifications:	<ul> <li>Table 7: Hold time for 74HC165 has been updated.</li> <li>The format of this data sheet has been redesigned to comply with the identity guidelines of Nexperia.</li> <li>Legal texts have been adapted to the new company name where appropriate.</li> </ul>					
74HC_HCT165 v.4	20151228	Product data sheet	-	74HC_HCT165 v.3		
Modifications:	Type numbers 74HC165N and 74HCT165N (SOT38-4) removed.					
74HC_HCT165 v.3	20080314	Product data sheet	-	74HC_HCT165_CNV v.2		
Modifications:	<ul> <li>The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors.</li> <li>Legal texts have been adapted to the new company name where appropriate.</li> <li>Package SOT763-1 (DHVQFN16) added to Section 4 and Section 12.</li> <li>Family data added, see Section 10</li> </ul>					
74HC_HCT165_CNV v.2	December 1990	Product specification	-	-		

### 15. Legal information

#### **Data sheet status**

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions".
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# **Contents**

1.	General description	1
2.	Features and benefits	1
3.	Applications	1
4.	Ordering information	2
5.	Functional diagram	2
6.	Pinning information	3
6.1	. Pinning	3
6.2	Pin description	4
7.	Functional description	4
8.	Limiting values	5
9.	Recommended operating conditions	6
10.	Static characteristics	6
11.	Dynamic characteristics	8
11.	Waveforms and test circuit	.11
12.	Package outline	14
13.	Abbreviations	18
14.	Revision history	18
15.	Legal information	19

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